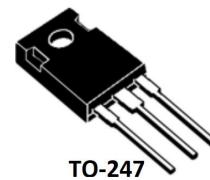


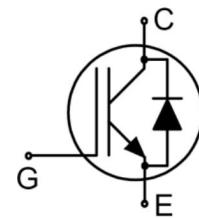
Features

- High Speed Switching & Low Power Loss
- $V_{CE(sat)}=1.95V$ @ $I_C=40A$
- $E_{off}=0.35mJ$ @ $T_c=25^\circ C$
- High Input Impedance
- $T_{rr}=80ns$ (Typ) @ $dI/F/dt=1000A/us$
- Maximum junction temperature $T_{vjmax}=175^\circ C$



Applications

- UPS
- PFC
- Welder
- IH Cooker
- PV Inverter



Absolute Ratings ($T_c=25^\circ C$)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	V_{ce}	650	V
Collector Current-continuous	I_c $T=25^\circ C$	80	A
	$T=100^\circ C$	40	A
Diode forward current	I_F $T=25^\circ C$	80	A
	$T_c=100^\circ C$	40	A
Collector Current-pulse (note 1)	I_{cm}	160	A
Gate-EMMitter Voltage	V_{GES}	± 30	V
Power Dissipation	PD	375	W
	$T_c=25^\circ C$	188	W
Operating Temperature Range	T_J	-40~+175	$^\circ C$
Storage Temperature Range	T_{STG}	-55~+150	$^\circ C$
Short Circuit Withstand Time	t_{sc}	5	us
Maximum Lead Temperature for Soldering Purposes	T_L	300	$^\circ C$

Electrical Characteristics

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Off-Characteristics						
Collector-Emitter Voltage	BV_{CES}	$I_c=2\text{mA}, V_{GE}=0\text{V}$	650	-	-	V
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=650\text{V}, V_{GE}=0\text{V}, T_c=25^\circ\text{C}$	-	-	40	μA
		$V_{CE}=650\text{V}, V_{GE}=0\text{V}, T_c=175^\circ\text{C}$	-	-	1000	
Gate-body leakage current, forward	I_{GESF}	$V_{CE}=0\text{V}, V_{GE}=20\text{V}$	-	-	100	nA
Gate-body leakage current, reverse	I_{GESR}	$V_{CE}=0\text{V}, V_{GE}=-20\text{V}$	-	-	-100	nA
On-Characteristics						
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_c=0.58\text{mA}$	4.8	5.8	6.8	V
Collector-Emitter saturation Voltage	V_{CESAT}	$V_{GE}=15\text{V} I_c=40\text{A} T_c=25^\circ\text{C}$	-	1.95	2.4	V
		$V_{GE}=15\text{V} I_c=40\text{A} T_c=175^\circ\text{C}$	-	2.3	-	V
Dynamic Characteristics						
Input capacitance	C_{IES}	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1.0\text{MHz}$	-	2818	-	pF
Output capacitance	C_{OES}		-	131	-	pF
Reverse transfer capacitance	C_{RES}		-	209	-	pF

Electrical Characteristics

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Switching Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC}=400\text{V}, I_c=40\text{A}, R_G=7.9\Omega, V_{GE}=15\text{V}, \text{Inductive Load}$ $T_c=25^\circ\text{C}$	-	58	-	ns
Turn-On rise time	t_r		-	54	-	ns
Turn-Off delay time	$t_{d(off)}$		-	245	-	ns
Turn-Off Fall time	t_f		-	40	-	ns
Turn-on Loss	E_{on}		-	1.15	-	mJ
Turn-off Loss	E_{off}		-	0.35	-	mJ
Total Loss	E_{ts}		-	1.50	-	mJ
Turn-on delay time	$t_{d(on)}$		-	61	-	ns

Turn-On rise time	tr	$R_G=7.9\Omega$, $V_{GE}=15V$, Inductive Load $T_c=175^\circ C$	-	60	-	ns
Turn-Off delay time	td(off)		-	260	-	ns
Turn-Off Fall time	t _f		-	38	-	ns
Turn-on switching Loss	E _{on}		-	1.80	-	mJ
Turn-off switching Loss	E _{off}		-	0.38	-	mJ
Total switching Loss	E _{ts}		-	2.18	-	mJ
Gate Charge	Q _g	$V_{CE}=520V, I_c=40A$ $V_{GE}=15V$	-	219	-	nC
Gate to Emitter Charge	Q _{ge}		-	26	-	nC
Gate to Collector Charge	Q _{gc}		-	115	-	nC
Anti-Parallel Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Voltage	V _F	$I_F=40A(T_J=25^\circ C)$	-	1.3	1.9	V
Diode Reverse recovery time	t _{rr}	$I_F=40A$ $dI_F/dt=1000A/us$ $T_J=25^\circ C$	-	80	-	ns
Diode Reverse recovery charge	Q _{rr}		-	1.0	-	uC
Diode Reverse recovery Current	I _{rr}		-	25	-	A

Thermal Characteristic

Paramer	Symbol	Max	Unit
Thermal Resistance,Junction to Case (IGBT)	R _{th(j-c)}	0.4	°C/W
Thermal Resistance,Junction to Case (Diode)	R _{th(j-c)}	1.2	°C/W
Thermal Resistance,Junction to Ambient	R _{th(j-A)}	40	°C/W

Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature

Electrical Characteristics(curves)

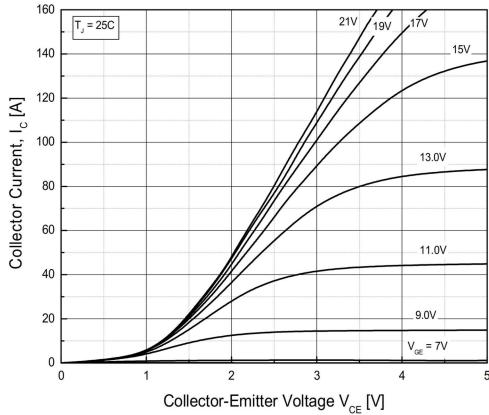


Fig.1 Typical Output Characteristics($T_j=25^\circ\text{C}$)

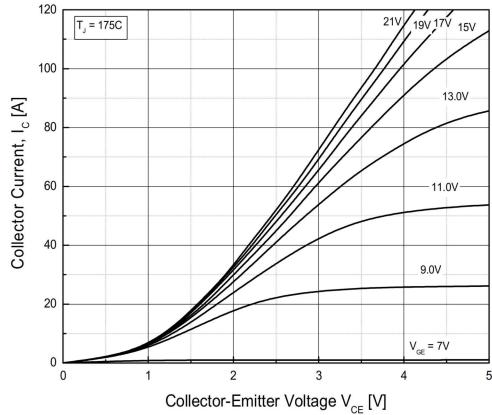


Fig.2 Typical Output Characteristics($T_j=175^\circ\text{C}$)

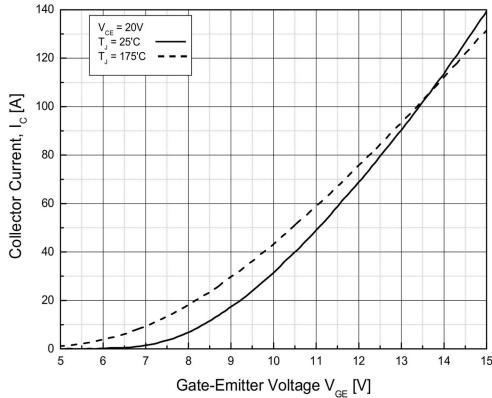


Fig.3 Typical Transfer Characteristics

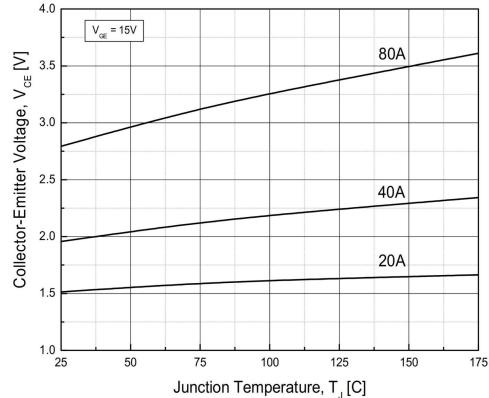


Fig.4 Typical Collector-Emitter Saturation Voltage - Junction Temperature

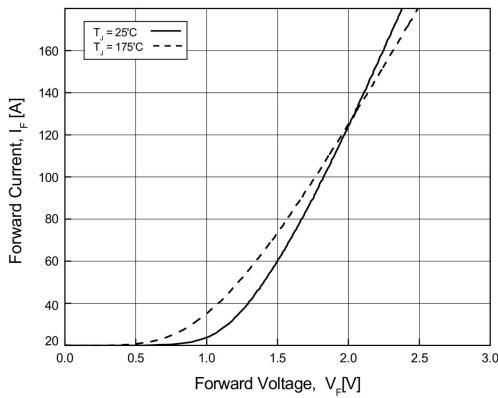


Fig.5 Diode Forward Characteristics

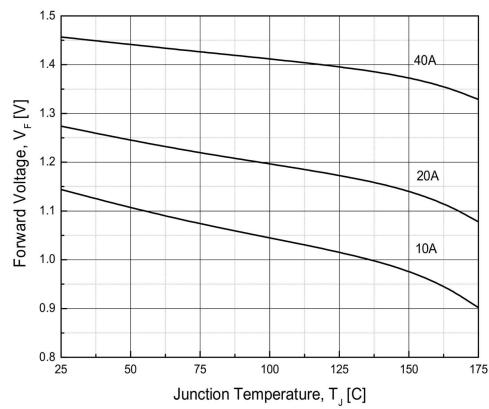


Fig.6 Diode Forward-Junction Temperature

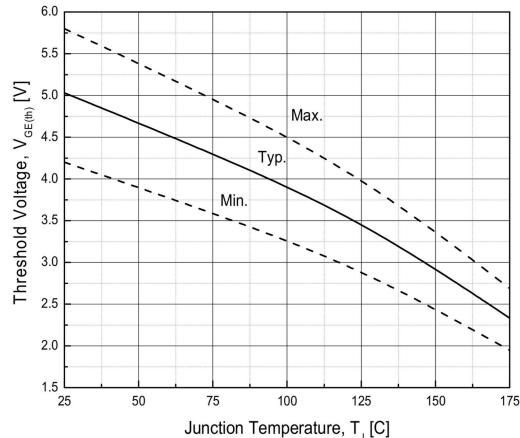


Fig.7 Threshold Voltage-Junction Temperature

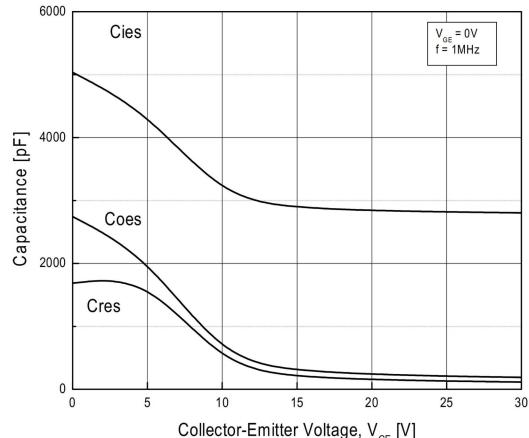


Fig.8 Typical Capacitance

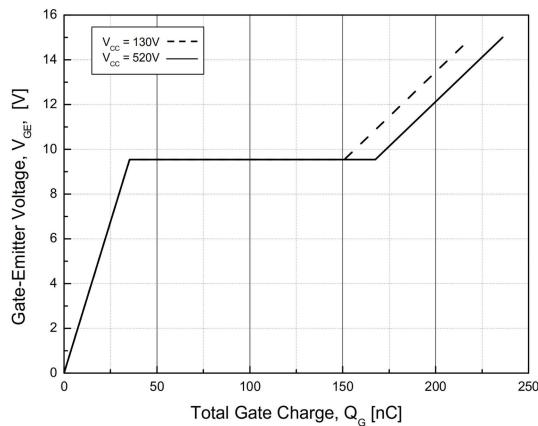


Fig.9 Typical Gate Charge

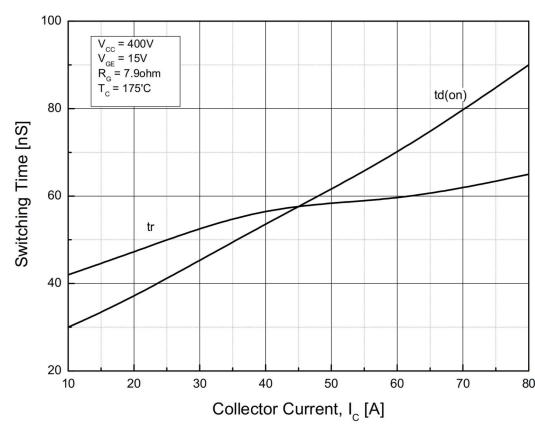


Fig.10 Typical Turn on-Collector Current

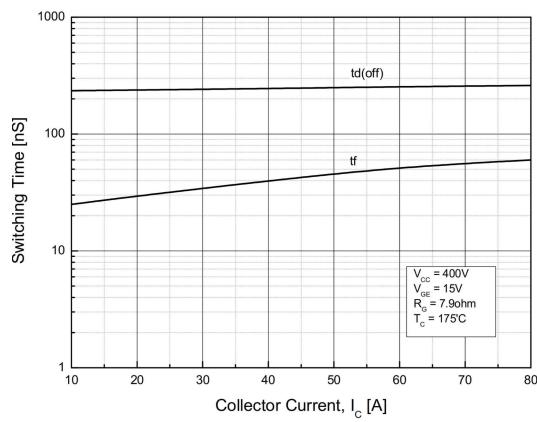


Fig.11 Typical Turn off-Collector Current

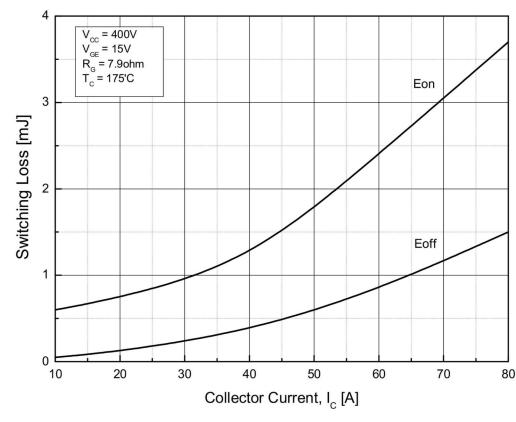
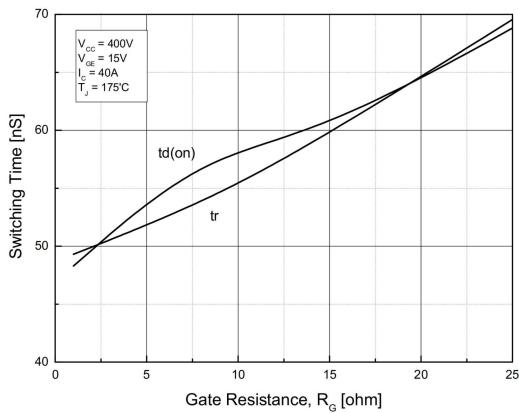
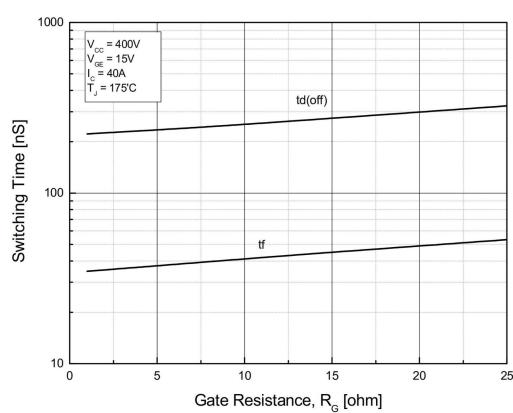
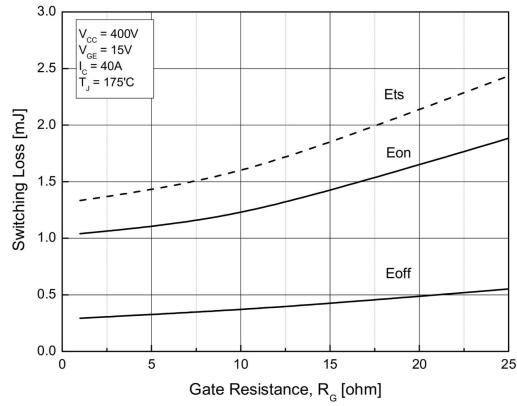
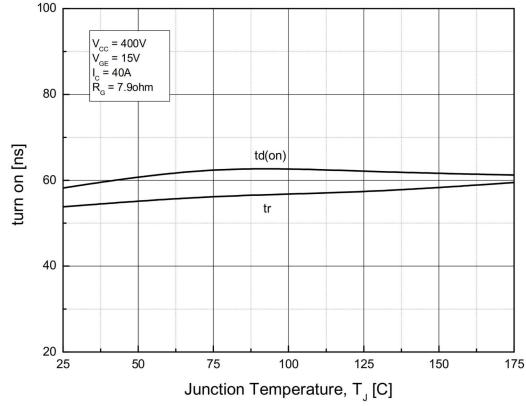
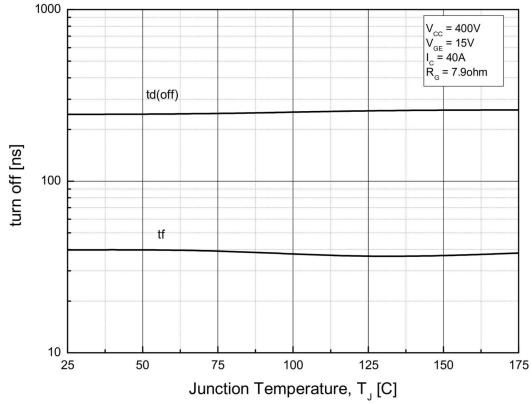
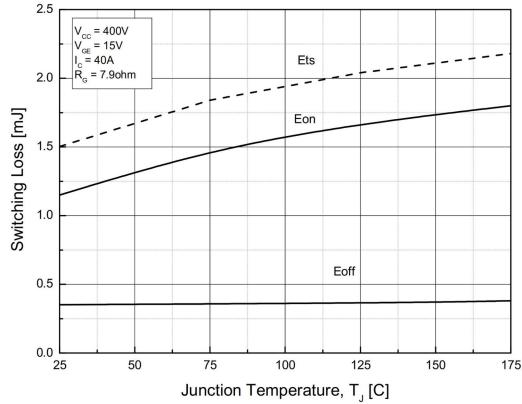
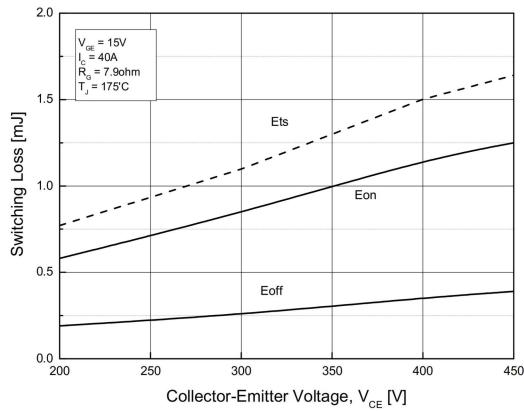
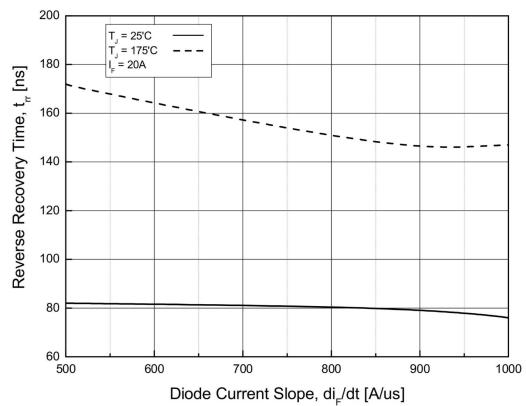
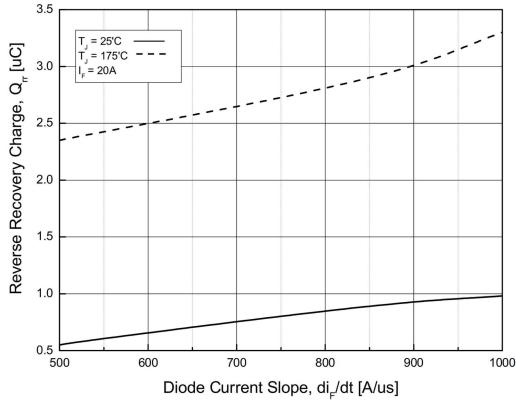
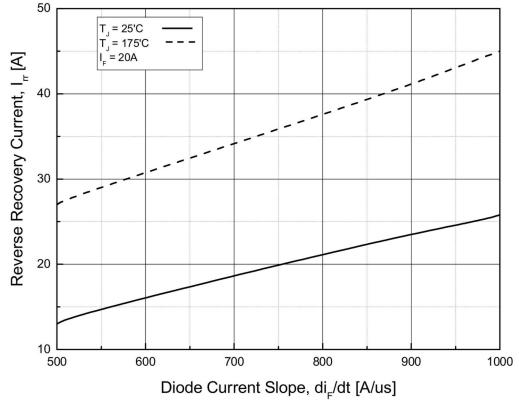
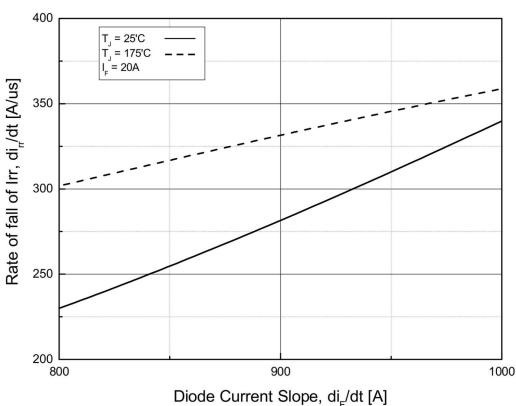
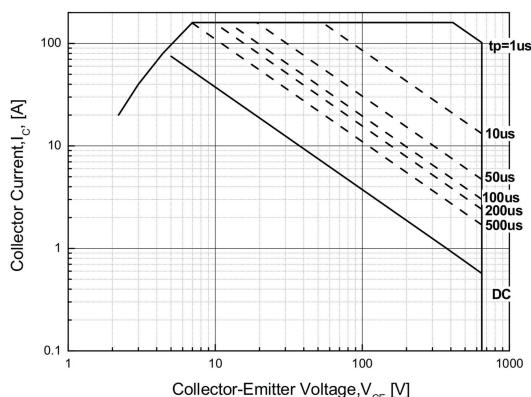


Fig.12 Switching Loss-Collector Current

**Fig.13 Turn on Characteristics-Gate Resistance****Fig.14 Turn off Characteristics-Gate Resistance****Fig.15 Switching Loss-Gate Resistance****Fig.16 Turn on Characteristics -Junction Temperature****Fig.17 Turn off Characteristics -Junction Temperature****Fig.18 Switching Loss-Junction Temperature**

**Fig.19** Switching Loss-Collector Emitter Voltage**Fig.20** Reverse Recovery Time
-Diode current slope**Fig.21** Reverse Recovery Charge
-Diode Current Slope**Fig.22** Reverse Recovery Current
-Diode current slope**Fig.23** Rate of fall of reverse recovery current
-Diode Current Slope**Fig.24** Forward Bias Safe Operating Area

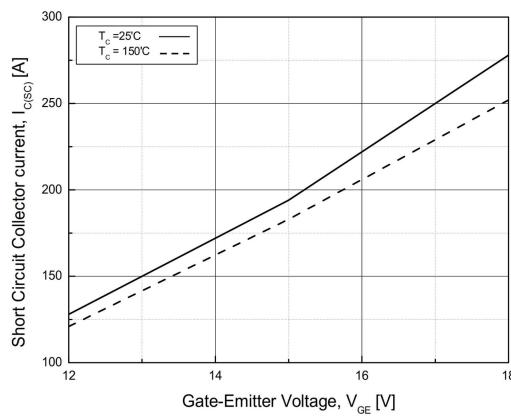


Fig.25 Typical Short Circuit Collector Current

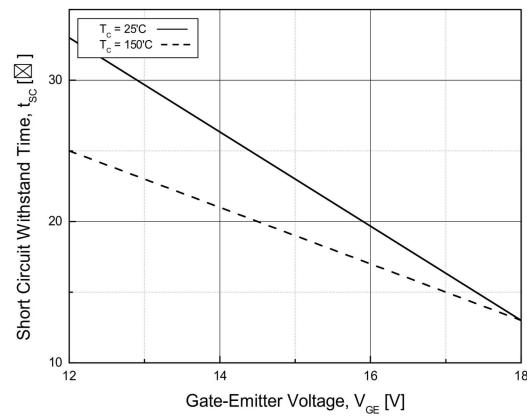


Fig.26 Typical Short Circuit Withstand Time

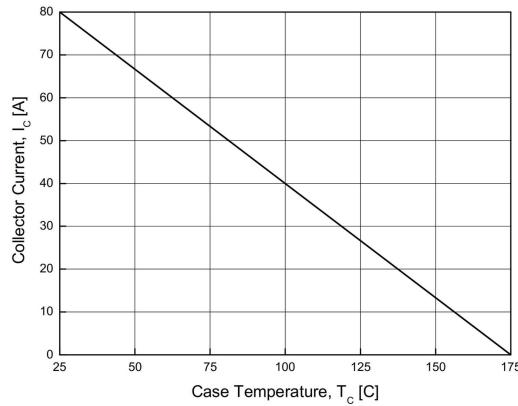


Fig.27 Case Temperature-Collector Current

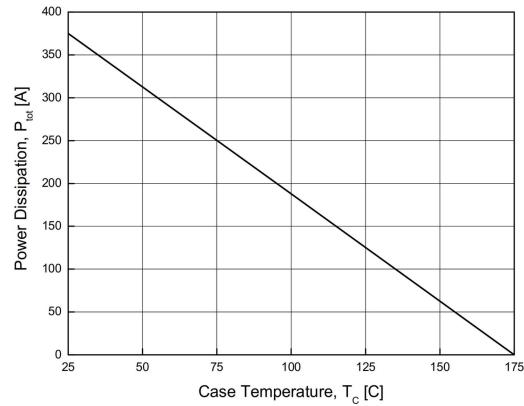


Fig.28 Power Dissipation-Case Temperature

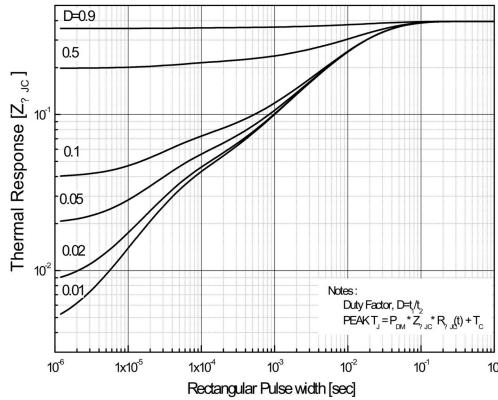


Fig.29 IGBT Transient Thermal Impedance

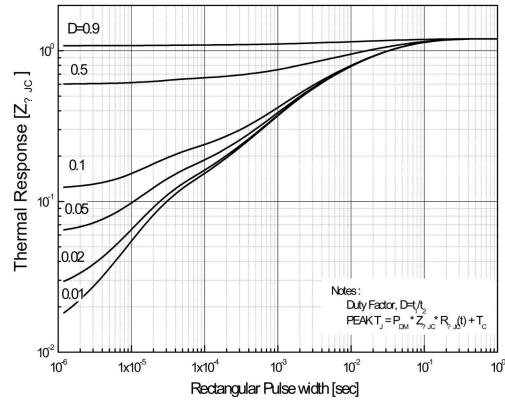


Fig.30 FRD Transient Thermal Impedance

Package Mechanical DATA

